Surface Mount Bridge Rectifier

Features

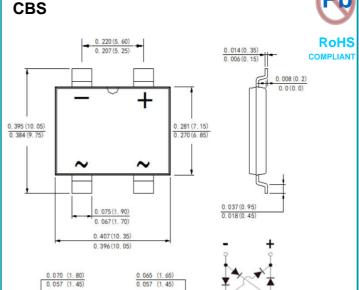
- Surface mount bridge, small package
- Ideal for printed circuit boards
- Glass passivated chip junction
- High forward current capability up to 6.0A
- High surge current capability
- High heat dissipation capability
- Low profile package
- Low forward voltage drop
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0

- Case:CBS
- Terminals:Matte tin plated leads, solderable per
- J-STD-002 and JESD22-B102
- High temperature soldering guaranteed
- Solder Reflow 260 °C,10seconds
- Polarity.:As marked on body
- Marking:Type number

Applications

• General purpose use in AC-to-DC bridge full wave rectification for Fast Charging, Switching Power Supply. USB PD, Adapter and 3-in-1 Power Board, etc.

Mechanical Data Epoxy meets UL-94V-0 Flammability rating



Reverse Voltage - 1000 Volts

Forward Current - 6.0 Amperes

Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

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Characteristics	Symbol	CBS610	Unit
Maximum Repetitive Peak Reverse Voltage	Vrrm	1000	V
Maximum RMS Voltage	VRMS	700	V
Maximum DC Blocking Voltage	VDC	1000	V
Maximum Average Forward	I(AV)	6.0	А
Rectified Output Current @ Ta=25°C			
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave,	IFSM	170	А
Superimposed on Rated Load (JEDEC Method)	IFSW		
I ² t Rating for Fusing (t<8.3mS)	l ² t	120	A ² s
Instantaneous forward voltage drop per Diode @IF=1.0A	VF	0.88	
@IF=3.0A		0.93	V
@IF=6.0A		0.96	
Maximum DC Reverse Current at Rated @T $_{J}$ =25 $^{\circ}$ C	lr.	5.0	
DC Bolcking Voltage per Diode @TJ=125°C	IR .	100	μА
Typical Junction Capacitance per Diode (Note1)	Cı	43	pF
Typical Thermal Resistance to Ambient	Røja	68	
Typical Thermal Resistance to case	Reлc	10	°C/W
Typical Thermal Resistance to lead	Rejl	22	
Operating Junction and StorageTemperature Range	TJ,TSTG	-55 to +150	°C

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 5.0V DC.



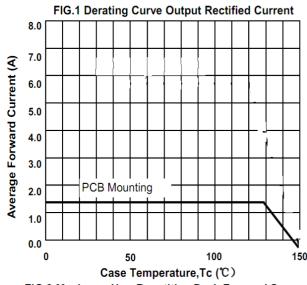


FIG.3 Maximum Non-Repetitive Peak Forward Surge **Current per Diode**

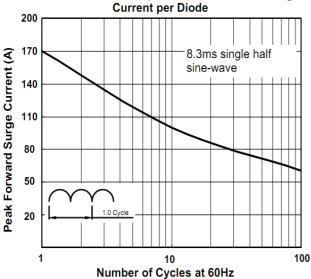


FIG.5 Typical Junction Capacitance per Diode

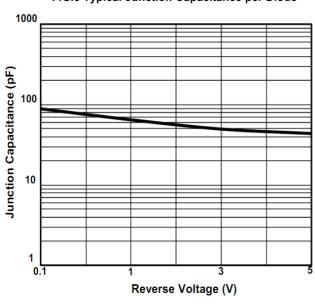
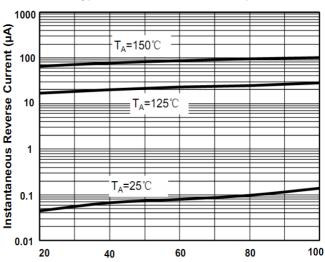
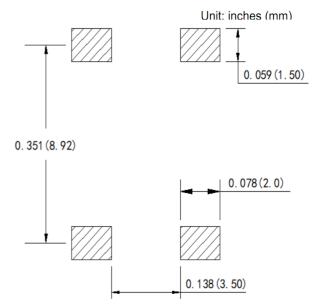


FIG.2 Typical Forward Characteristics per Diode 100 Instantaneous Forward Current (A) T_A=125℃ 10 T_A=25℃ 0.01 0.4 0.5 0.6 0.7 8.0 0.9 1.0 1.1 Instantaneous Forward Voltage (V)

FIG.4 Typical Reverse Characteristics per Diode



Percent of Rated Peak Reverse Voltage (%) Suggested PCB printfoot layout





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